

EV Group announces NanoCleave™ layer release technology for advanced semiconductor packaging – September 22, 2022

EVG introduced NanoCleave[™], a revolutionary layer release technology for silicon that enables ultra-thin layer stacking for front-end processing, including advanced logic, memory and power device formation, as well as semiconductor advanced packaging. NanoCleave enables silicon wafer carriers in advanced packaging processes such as Fan-out Wafer-level Packaging (FoWLP) using mold and reconstituted wafers as well as interposers for 3D Stacked ICs (3D SIC). The nanometer precision of IR laser-initiated cleaving opens up the possibility of processing extremely thin device wafers without changing processes of record. Subsequent stacking of such thin device layers enables higher bandwidth interconnects and opens up new opportunities to design and segment dies for next-generation high-performance systems.

